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H140A

特性/ Features

Tg135±5℃ (DSC)

可依需求提供多种Tg值 / Different Tg available upon request Tg : 140±5℃、Tg≥140℃

UV Blocking 与 AOI兼容可提高PCB生产效率

UV Blocking and AOI compatible, so as to increase productivity efficiency

可依需求提供仪表专用的FR-4 板材/ the meter appropriate FR-4 CCL upon request

可依需求提供具 UV阻挡功能的自然色板材/ UV Blocking and natural color CCL upon request

可依需求提供不具UV阻挡功能的自然色板材 (白料) / No UV Blocking and natural color CCL upon request

应用领域/ Applications

适合于2-6层PCB、计算机及外围设备、通讯设备、办公自动设备等。

Suitable for medium multilayer printed circuit board, computer, communication equipment, OA equipment, etc.

主要特性 / General properties

检测项目 Item	单位 Unit	检测条件 Test Condition	规范值 Spec	典型值 Typical Value
玻璃化转变温度 Tg	℃	DSC	135±5	135.5
剥离强度 1oz Peel Strength	N/mm	288℃, 10S	≥1.40	1.81
热应力 Thermal stress	S	288℃, solder dip	> 10	120s No delamination
弯曲强度 Flexural Strength	N/mm ²	经向LW	≥415	580
		纬向CW	≥345	485
燃烧性 Flammability	—	E 24/125	UL94V-0	V-0
表面电阻 Surface Resistivity	MΩ	After moisture	≥1.0×10 ⁴	5.16×10 ⁷
体积电阻 Volume Resistivity	MΩ·cm	After moisture	≥1.0×10 ⁶	5.07×10 ⁸
介电常数 Dielectric Constant	—	1 MHZ C 24/23/50	≤5.4	4.8
介质损耗角正切 Loss Tangent	—	1 MHZ C 24/23/50	≤0.035	0.015
耐电弧 Arc Resistance	S	D48/50+D0.5/23	≥60	125
击穿电压 Dielectric Breakdown	KV	D48/50+D0.5/23	≥40	58
吸水率 Moisture Absorption	%	D24/23	≤0.8	0.15
热分解温度 Td	℃	Weight Loss 5%	—	310
CTE Z-axis	Alpha 1	ppm /℃	TMA	—
	Alpha 2	ppm /℃		—
	50 - 260 ℃	%		—
T288	min	TMA	—	2
相比漏电起痕指数 CTI	V	IEC-60112	175~250	200

Specimen Thickness : 1.6mm ;

Explanation: C: Humidity conditioning;

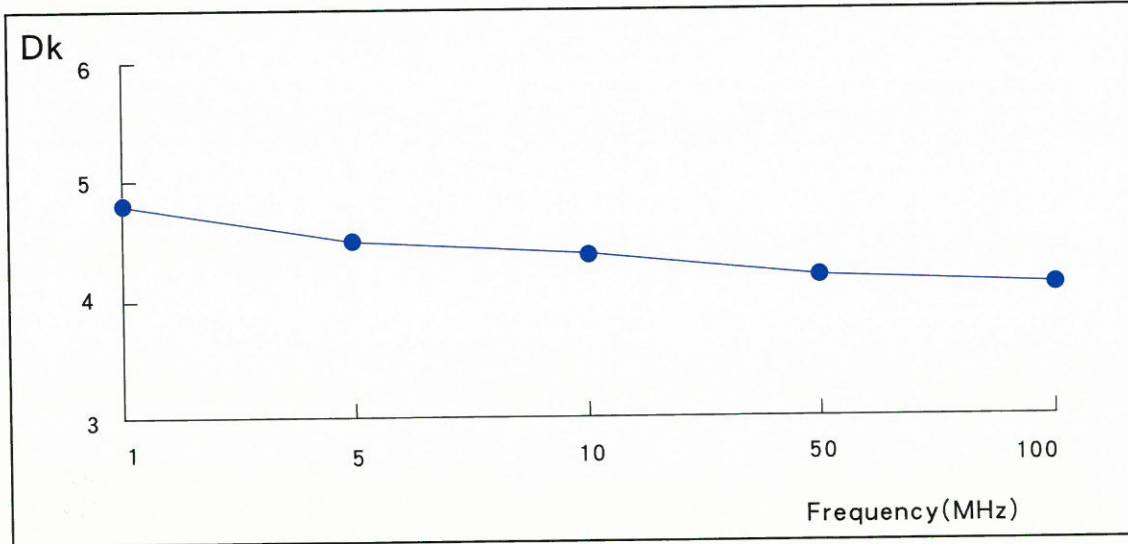
D: Immersion conditioning in distilled water ;

E: Temperature conditioning ;

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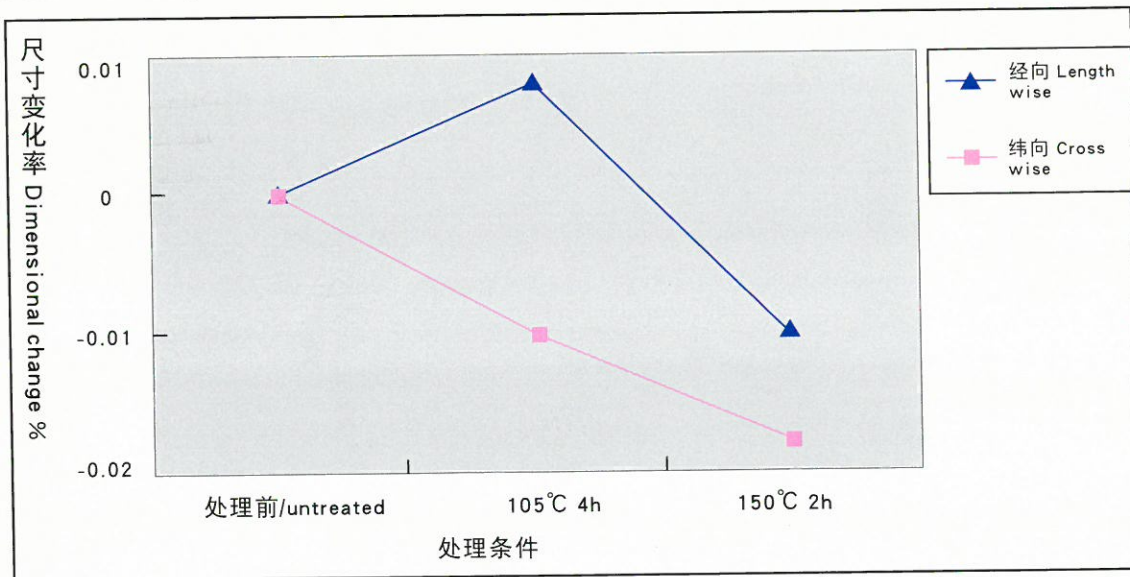
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◆ 介电常数 / Dielectric constant



◆ 热处理后板材经纬向尺寸变化

Dimensional change in cross and length direction after heat treatment



◆ 产品系列 / Purchasing information

厚度Thickness	铜箔Copper foil	标准尺寸 Standard size
0.10-3.2mm	12um - 105um	37"×49"、41"×49"、43"×49"

※ Other sheet size and thickness could be available upon request